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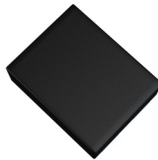
Features

- $BV_{CEO} > 45V$
- Low profile 0.4mm high package for thin applications
- Ultra-Small Surface Mount Package
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

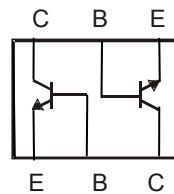
Mechanical Data

- Case: X2-DFN1310-6
- Nominal package height: 0.4mm
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu, Solderable per MIL-STD-202, Method 208 
- Weight: 0.0015 grams (approximate)

X2-DFN1310-6



Top View



Device Schematic
Top View

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
BC847CDLP-7	1M	7	8	3000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



(Top View)

1M = Product Type Marking Code

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	50	V
Collector-Emitter Voltage	V _{CE0}	45	V
Emitter-Base Voltage	V _{EB0}	6	V
Collector Current	I _C	100	mA

Thermal Characteristics – Total Device (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) Total Device	P _D	350	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Note: 5. For a device surface mounted on minimum recommended pad layout FR-4 PCB with single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

Thermal Characteristics – Total Device

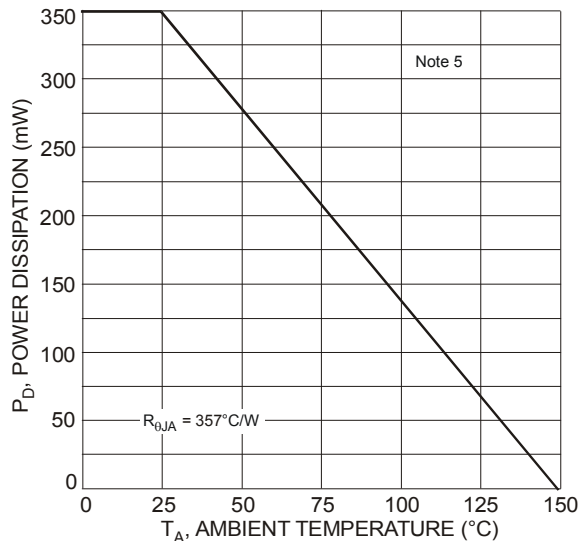


Figure 1 Power Dissipation vs. Ambient Temperature

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic (Note 6)	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	50	—	—	V	$I_C = 100\mu\text{A}, I_B = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	45	—	—	V	$I_C = 10\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	6	—	—	V	$I_E = 100\mu\text{A}, I_C = 0$
DC Current Gain	h_{FE}	420	650	800	—	$V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	55 130	250 600	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	—	700 900	—	mV	$I_C = 10\text{mA}, I_B = 0.5\text{mA}$ $I_C = 100\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Voltage	$V_{BE(on)}$	580 —	660 —	700 770	mV	$V_{CE} = 5.0\text{V}, I_C = 2.0\text{mA}$ $V_{CE} = 5.0\text{V}, I_C = 10\text{mA}$
Collector-Cutoff Current	I_{CES}	—	—	15	nA	$V_{CE} = 50\text{V}$
Collector-Cutoff Current	I_{CBO}	—	—	15 5	nA μA	$V_{CB} = 30\text{V}$ $V_{CB} = 30\text{V}, T_A = +150^\circ\text{C}$
Gain Bandwidth Product	f_T	100	—	—	MHz	$V_{CE} = 5.0\text{V}, I_C = 10\text{mA},$ $f = 100\text{MHz}$
Collector-Base Capacitance	C_{CBO}	—	2.0	—	pF	$V_{CB} = 10\text{V}, f = 1.0\text{MHz}$

Note: 6. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

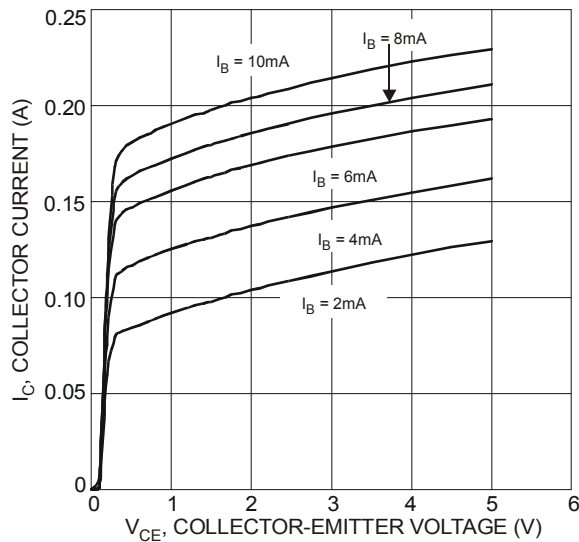


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

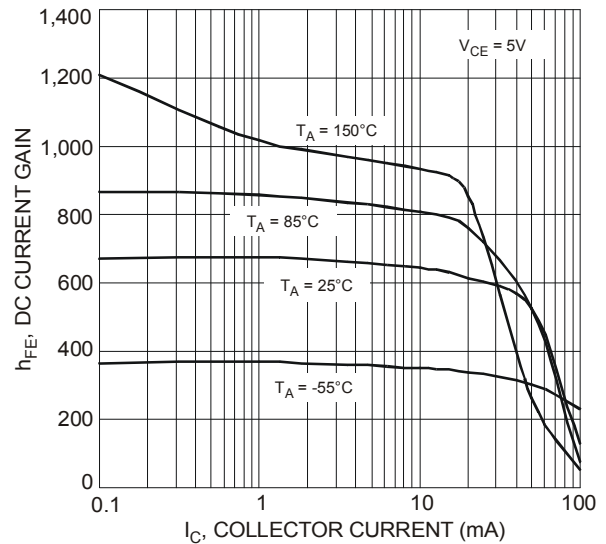


Figure 3 Typical DC Current Gain vs. Collector Current

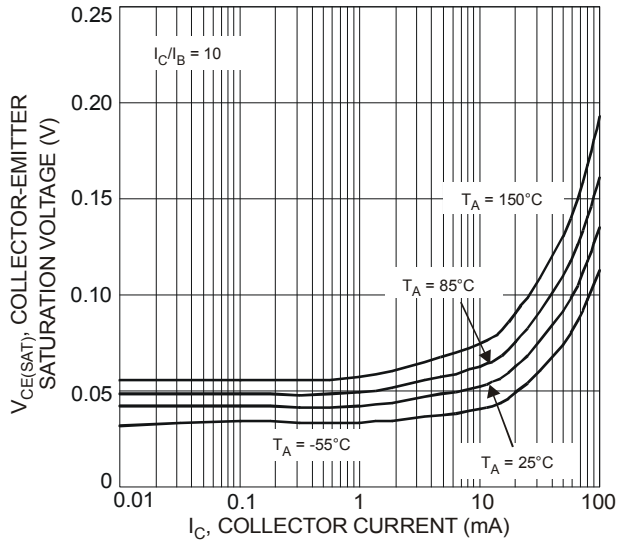


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

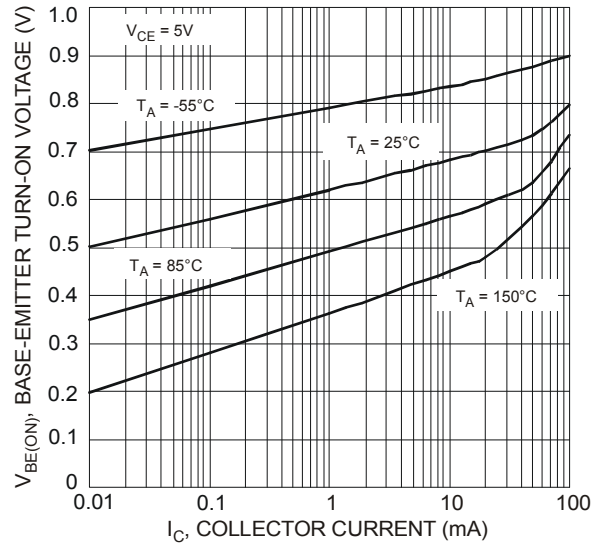


Figure 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

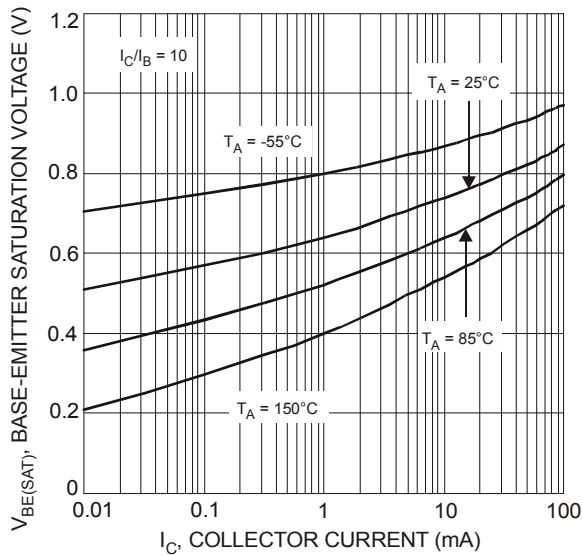


Figure 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

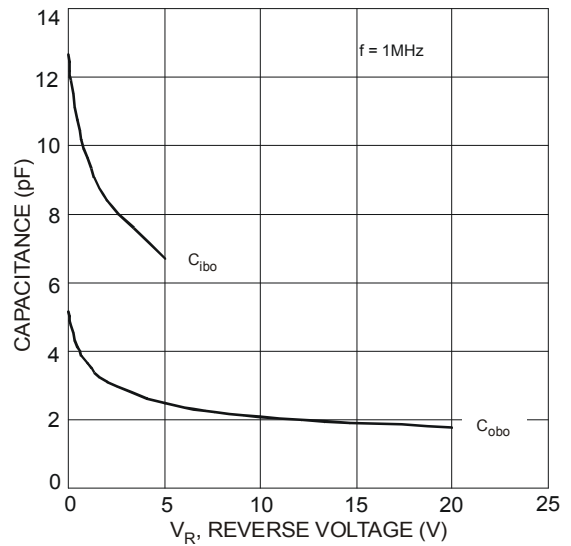


Figure 7 Typical Capacitance Characteristics

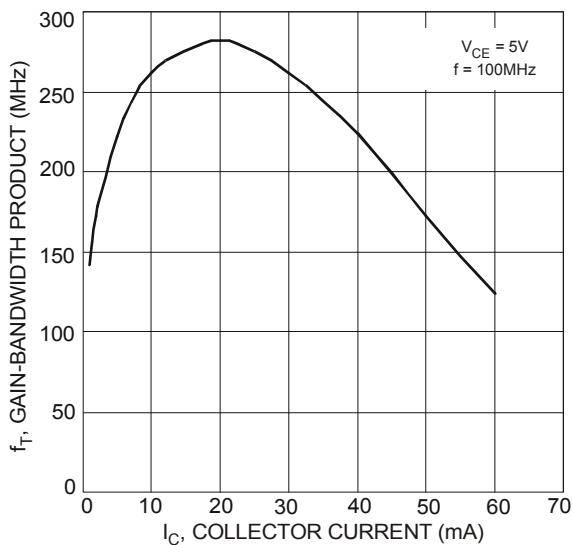
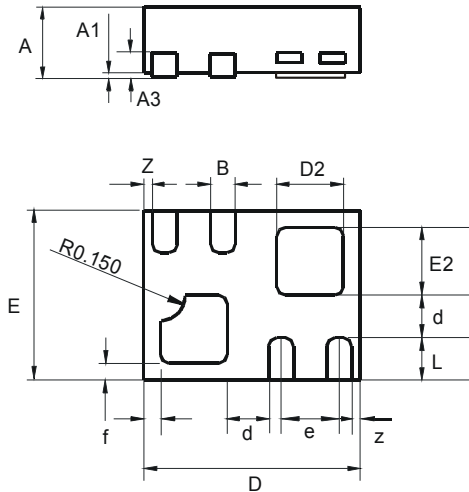


Figure 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

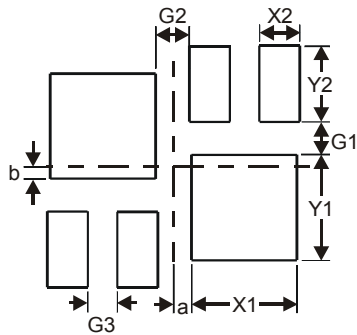
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X2-DFN1310-6			
Dim	Min	Max	Typ
A	—	0.40	—
A1	0	0.05	0.02
A3	—	—	0.13
b	0.10	0.20	0.15
D	1.25	1.38	1.30
d	—	—	0.25
D2	0.30	0.50	0.40
E	0.95	1.075	1.00
e	—	—	0.35
E2	0.30	0.50	0.40
f	—	—	0.10
L	0.20	0.30	0.25
Z	—	—	0.05
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
G1	0.16
G2	0.17
G3	0.15
X1	0.52
X2	0.20
Y1	0.52
Y2	0.375
a	0.09
b	0.06

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